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## **ON Semiconductor**®

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# N-Channel PowerTrench<sup>®</sup> MOSFET 100 V, 11.2 A, 9.8 m $\Omega$

#### Features

- Max  $r_{DS(on)}$  = 9.8 m $\Omega$  at V<sub>GS</sub> = 10 V, I<sub>D</sub> = 11.2 A
- Max  $r_{DS(on)}$  = 16 m $\Omega$  at V<sub>GS</sub> = 6 V, I<sub>D</sub> = 9 A
- High performance trench technologh for extremely low r<sub>DS(on)</sub>
- High power and current handing capability in a widely used surface mount package
- 100% UIL Tested
- RoHS Compliant

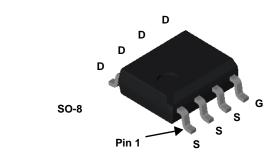


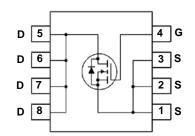
### **General Description**

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench<sup>®</sup> process that has been optimized for  $r_{DS(on)}$ , switching performance and ruggedness.

### Applications

- DC/DC Converters and Off-Line UPS
- Distributed Power Architectures and VRMs
- Primary Swith for 24 V and 48 V Systems
- High Voltage Synchronous Rectifier





#### MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Paramet	er		Ratings	Units
V <sub>DS</sub>	Drain to Source Voltage			100	V
V <sub>GS</sub>	Gate to Source Voltage			±20	V
1	Drain Current -Continuous			11.2	٨
D	-Pulsed			50	Α
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	264	mJ
D	Power Dissipation	T <sub>C</sub> = 25 °C	(Note 1)	5.0	W
P <sub>D</sub>	Power Dissipation $T_A = 25 \text{ °C}$ (Note 1a)			2.5	vv
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperatu	ure Range		-55 to +150	°C

#### **Thermal Characteristics**

$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case	(Note 1)	25	°C/W
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	C/VV

#### **Package Marking and Ordering Information**

Device Marking Device		Package	Reel Size	Tape Width	Quantity	
FDS86140	FDS86140	SO-8	13"	12 mm	2500 units	

	E
Units	FDS861
V	40 N-
mV/°C	Ċ
μA nA	ar
nA	n,
	el Po
V	¥
mV/°C	/erT
mΩ	140 N-Channel PowerTrench <sup>®</sup>
S	Z
	OSF
pF	Ш
- <b>F</b>	

Off Char	acteristics						
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0 \ V$	100			V	
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu\text{A},$ referenced to 25 °C		70		mV/°C	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 80 V, V_{GS} = 0 V$			1	μΑ	
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20 V, V_{DS} = 0 V$			±100	nA	
On Chara	acteristics						
V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \ \mu A$	2	2.7	4	V	
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \ \mu$ A, referenced to 25 °C		-11		mV/°C	
	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 11.2 \text{ A}$	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 11.2 A		8.1	9.8		
r	Static Drain to Source On Resistance	V <sub>GS</sub> = 6 V, I <sub>D</sub> = 9 A		10.8	16	mΩ	
r <sub>DS(on)</sub>		$V_{GS} = 10$ V, $I_D = 11.2$ A, $T_J = 125$ °C		13.1	17	- 11152	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 11.2 A		35		S	
Dynamic	Characteristics						
C <sub>iss</sub>	Input Capacitance	V 50.V.V. 0.V.		1940	2580	pF	
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 0 V, f = 1 MHz		440	585	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			20	30	pF	
R <sub>g</sub>	Gate Resistance			0.9		Ω	
Switchin	SS Drain to Source Breakdown Voltage   SS Breakdown Voltage Temperature   Coefficient Zero Gate Voltage Drain Current   Gate to Source Leakage Current Gate to Source Threshold Voltage   Sthip Gate to Source Threshold Voltage   Gate to Source Threshold Voltage Temperature Coefficient   n) Static Drain to Source On Resistance   Forward Transconductance Input Capacitance   Output Capacitance Reverse Transfer Capacitance						
t <sub>d(on)</sub>	Turn-On Delay Time			13.7	25	ns	
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 50 V, I <sub>D</sub> = 11.2 A,		5.6	11	ns	
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, \text{ R}_{GEN} = 6 \Omega$		23	38	ns	
t <sub>f</sub>	Fall Time			4.8	10	ns	
-				1	1	1 -	

**Test Conditions** 

Min

Тур

Max

C <sub>iss</sub>	Input Capacitance		1940	2580	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 0 V, f = 1 MHz	440	585	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		20	30	pF
Rg	Gate Resistance		0.9		Ω

•					
t <sub>d(on)</sub>	Turn-On Delay Time		13.7	25	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 50 V, I <sub>D</sub> = 11.2 A,	5.6	11	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, \text{ R}_{GEN} = 6 \Omega$	23	38	ns
t <sub>f</sub>	Fall Time		4.8	10	ns
Qg	Total Gate Charge	$V_{GS} = 0$ V to 10 V	29	41	nC
Qg	Total Gate Charge	$V_{GS} = 0 V \text{ to } 5 V$ $V_{DD} = 50 V,$ $I_D = 11.2 A$	16.5	23	nC
Q <sub>gs</sub>	Gate to Source Charge	I <sub>D</sub> = 11.2 A	8.0		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		6.5		nC

### **Drain-Source Diode Characteristics**

Electrical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

Parameter

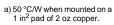
$V_{SD}$	Source-Drain Diode Forward Voltage	$V_{GS} = 0 V, I_S = 11.2 A$ (Note 2)	0.8	1.3	V
		$V_{GS} = 0 V, I_S = 2 A$ (Note 2)	0.7	1.2	
t <sub>rr</sub>	Reverse Recovery Time		53	85	ns
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> = 11.2 A, di/dt = 100 A/μs	59	94	nC

NOTES:

Symbol

1. R<sub>01A</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0JC</sub> is guaranteed by design while R<sub>0CA</sub> is determined by the user's board design.

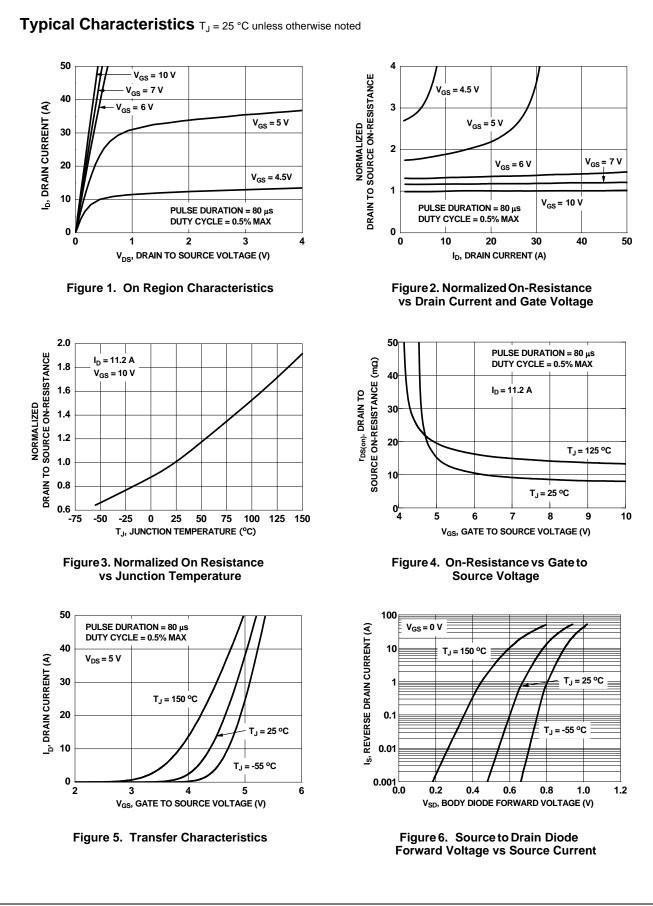




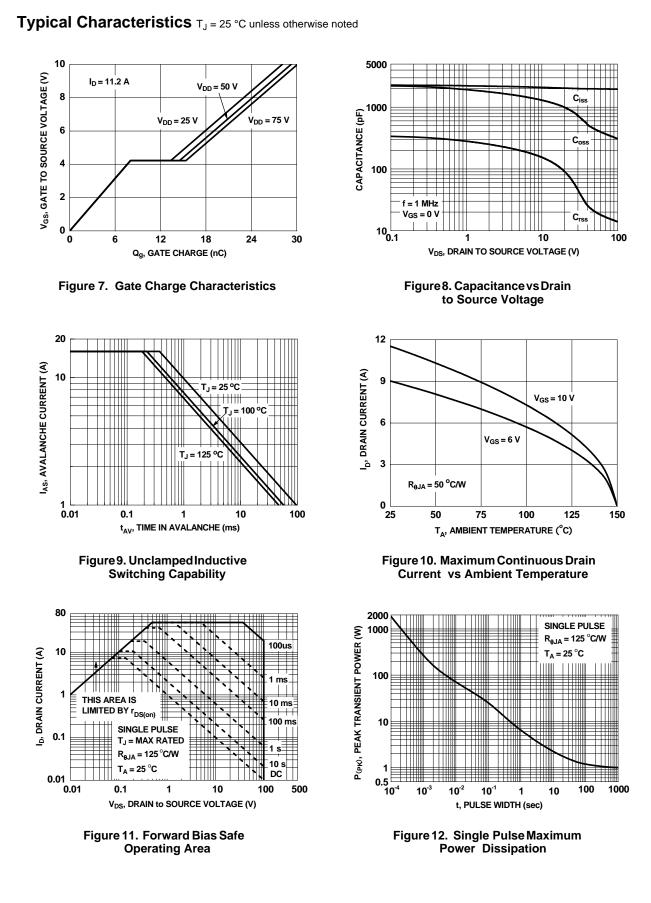


b) 125 °C/W when mounted on a minimum pad.

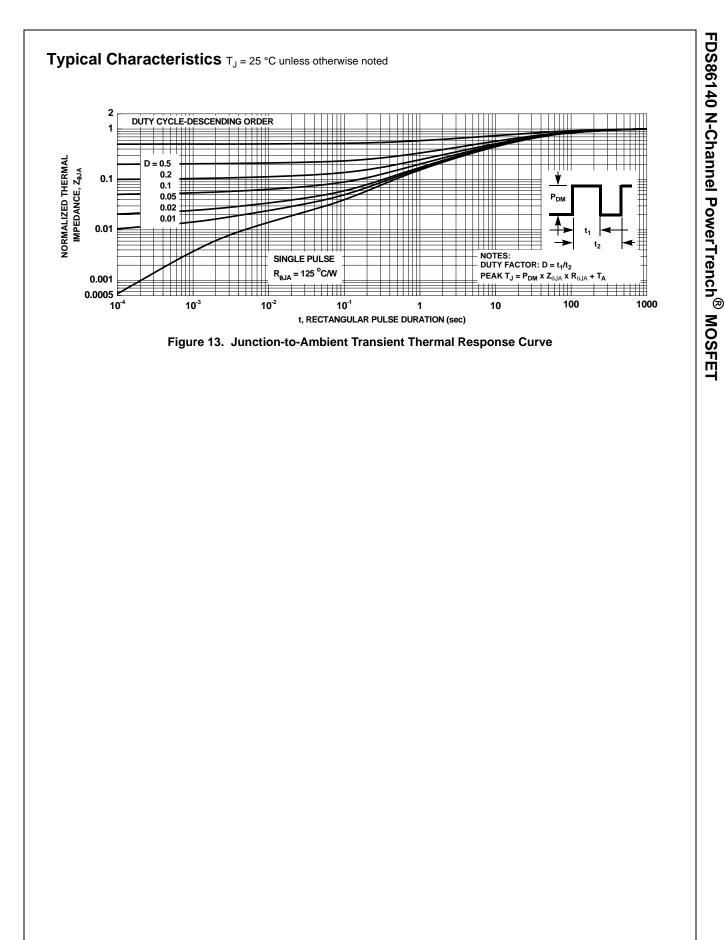
2. Pulse Test: Pulse Width < 300  $\mu s,$  Duty cycle < 2.0%. 3. Starting T\_J = 25 °C, L = 1 mH, I\_{AS} = 23 A, V\_{DD} = 90 V, V\_{GS} = 10 V.

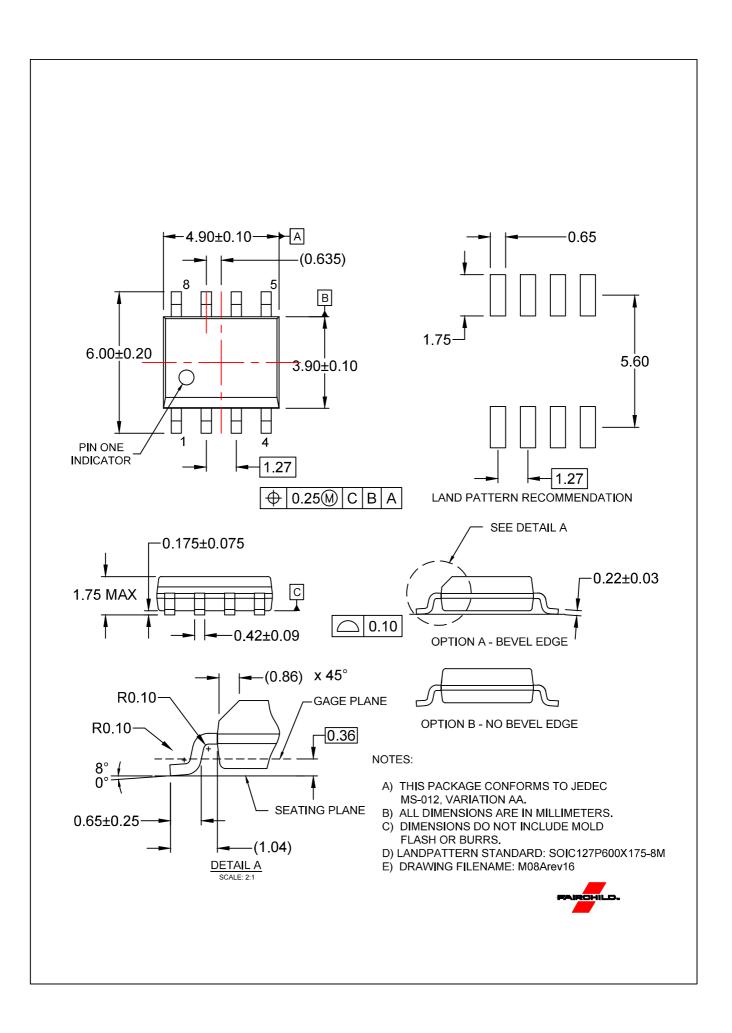


FDS86140 N-Channel PowerTrench<sup>®</sup> MOSFET



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